



100% Material Declaration Data Sheet for 7 Series FBG676

PK552 (v1.1) November 16, 2012

Average Weight: 2.9376g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					0.388303	13.218
	Silicon (Si)	7440-21-3	100.00	Basis	0.388303	
Solder Bump					0.018136	0.617
	Tin (Sn)	7440-31-5	63.00	Basis	0.011426	
	Lead (Pb)	7439-92-1	37.00	Basis	0.006710	
Solder Paste					0.003700	0.126
	Tin (Sn)	7440-31-5	96.50	Basis	0.003571	
	Silver (Ag)	7440-22-4	3.00	Basis	0.000111	
	Copper (Cu)	7440-50-8	0.50	Basis	0.000019	
Capacitor 1					0.010800	0.368
	BaTiO3 type	12047-27-7	70.60	Ceramic	0.007625	
	Nickel (Ni)	7440-02-0	6.70	Inner electrode	0.000724	
	Copper (Cu)	7440-50-8	20.10	Outer electrode	0.002171	
	Nickel (Ni)	7440-02-0	0.80	Plating 1	0.000086	
	Tin (Sn)	7440-31-5	1.80	Plating 2	0.000194	
Capacitor 2					0.001200	0.041
	BaTiO3 type	12047-27-7	66.00	Ceramic	0.000792	
	Copper (Cu)	7440-50-8	2.67	Inner electrode	0.000032	
	Nickel (Ni)	7440-02-0	23.33	Outer electrode	0.000280	
	Nickel (Ni)	7440-02-0	2.33	Plating 1	0.000028	
	Tin (Sn)	7440-31-5	5.67	Plating 2	0.000068	
Capacitor 3					0.007440	0.253
	BaTiO3 type	12047-27-7	51.10	Ceramic	0.003802	
	Nickel (Ni)	7440-02-0	27.00	Inner electrode	0.002009	
	Copper (Cu)	7440-50-8	16.00	Outer electrode	0.001190	
	Glass	65997-17-3	0.90	Plating1	0.000067	
	Nickel (Ni)	7440-02-0	2.00	Plating 1	0.000149	
	Tin (Sn)	7440-31-5	3.00	Plating 2	0.000223	

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Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Underfill					0.049000	1.668
	Bisphenol F/ epichlorohydrin copolymer	9003-36-5	20.00	Basis	0.009800	
	Phenolic Resin	Trade Secret	15.00	Basis	0.007350	
	Bisphenol A type liquid epoxy resin	25068-38-6	5.00	Basis	0.002450	
	Amine type accelerator	Trade Secret	5.00	Basis	0.002450	
	Silicon Dioxide	60676-86-0	51.50	Basis	0.025235	
	Carbon Black	1333-86-4	1.00	Basis	0.000490	
	Additives	Trade Secret	2.50	Additive	0.001225	
Solder Ball					0.564707	19.223
	Tin (Sn)	7440-31-5	96.50	Main Material	0.544942	
	Silver (Ag)	7440-22-4	3.00	Main Material	0.016941	
	Copper (Cu)	7440-50-8	0.50	Main Material	0.002824	
Substrate					1.894314	64.485
	Copper (Cu)	7440-50-8	37.00		0.700896	
	Tin (Sn)	7440-31-5	1.67		0.031635	
	Lead (Pb)	7439-92-1	0.33		0.006251	
	Silver (Ag)	7440-22-4	0.03		0.000568	
	BT Core	N/A	49.35		0.934844	
	ABF	N/A	11.49		0.217657	
	Solder Mask	N/A	0.13		0.002463	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
03/23/2012	1.0	Initial Xilinx release.
11/16/2012	1.1	Update substrate component

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